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(54) Title: SUBSTRATE WHICH IS MADE FROM PAPER AND IS PROVIDED WITH AN INTEGRATED CIRCUIT			
(57) Abstract			
The invention relates to a substrate (1) which is made from paper and is provided with at least one integrated circuit (3) which is produced from a semiconductive organic polymer. A semiconductive organic polymer of this nature, when used as the base material for the integrated circuit (3), leads to the possibility of directly producing the substrate (1) in the required thickness, to the need for support layers and/or protective layers being eliminated, and to the possibility of reducing the cost price of the substrate (1) compared to substrates which comprise an integrated circuit (3) of the silicon type.			